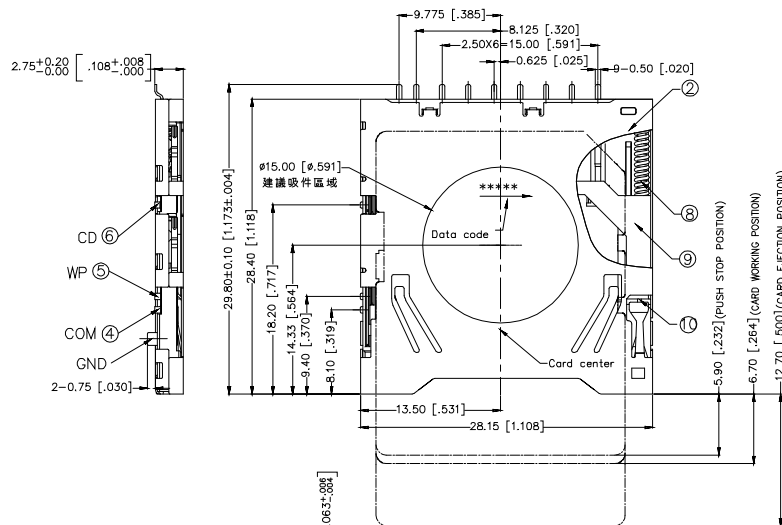
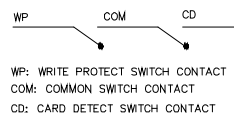


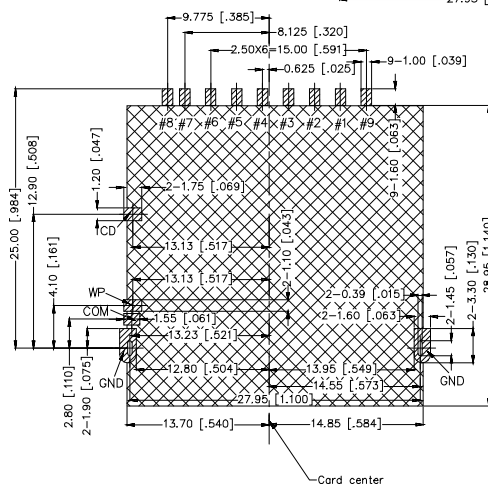
#1	CD/DAT3
#2	CMD
#3	VSS
#4	VDD
#5	CLK
#6	VSS
#7	DAT0
#8	DATE1
#9	DATE2

SD SIGNAL PIN DEFINE



Switch Operation Diagram

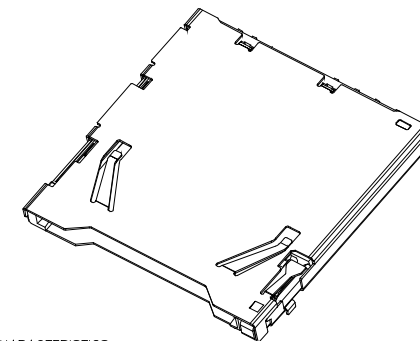
ELECTRIC FUNCTION	WRITE PROTECT SWITCH				CARD DETECT SWITCH	
	WRITE UNABLE	WRITE ENABLE	WRITE UNABLE	WRITE ENABLE	MMC	SD
CARD NAME	MMC	SD	MMC	SD	MMC	SD
WITHOUT CARD		OPEN		OPEN	OPEN	OPEN
CARD INSERTED		OPEN		CLOSE	CLOSE	CLOSE
SWITCH DIAGRAM	WP — COM				COM — CD	



RECOMMENDED P.C.B. LAYOUT

PCB DIMENSION DEFAULT TOLERANCE: ±0.05

- RECOMMENDED SOLDER PAD AREA
- TRACE KEEP OUT AREA



SPECIFICATION

- ELECTRICAL CHARACTERISTICS:
 - CONTACT CURRENT RATING: 0.5A MAX.
 - CONTACT RESISTANCE: 100 mOHMS MAX.
 - OPERATING VOLTAGE: 3.3V.
 - INSULATION RESISTANCE:
 - INITIAL: 1000 MOHMS MIN.
 - AFTER TEST: 100 MOHMS MIN.
 - OPERATING CURRENT: 0.1A MAX.
- MECHANICAL CHARACTERISTICS:
 - TOTAL MATING FORCE: 40N MAX.
 - DURABILITY: 10000 CYCLES.
- ENVIRONMENT CHARACTERISTICS:
 - OPERATING TEMPERATURE: -25°C~85°C
 - STORAGE TEMPERATURE: -40°C~85°C
- CARD OPERATION GUIDE:
 - COMPATIBLE CARD: SD&SDIO&MMC CARD
 - CARD INSERT DIRECTION:
 - THE CARD SIDE WITH ELECTRIC PAD SHOULD BE AGAINST TOP SHIELD
- RECOMMENDED IR REFLOW PORCESS PEAK TEMPERATURE: 250±5°C, TIME 10s MAX.
- ALL SMT CONTACTS AND PADS CO-PLANARITY: 0.10mm MAX
- DON'T PERMIT TO BE PROCEEDED SMT RE-FLOW PROCESS WHEN PUSH-PUSH FEATURE IS IN WORKING POSITION

10	CAM FOLLOWER	1	SUS304		
9	SLIDER	1	HTN	COLOR: BLACK	
8	SPRING	1	SWP		
7	SIGNAL CONTACT	9	PH/BR	50-100μ" Ni UNDERPLATING OVER ALL 100-200μ" LEAD FREE TIN ALLOY PLATING AT SOLDERING AREA 350° Min Au OR 300° Min PLATING 5-10μ Au PLATING AT CONTACT AREA	
6	DETECT SWITCH CONTACT	1	PH/BR	50-100μ" Ni UNDERPLATING OVER ALL 50-100μ Au PLATING AT SOLDERING AREA 10μ Au PLATING AT CONTACT AREA	
5	WRITE PROTECT SWITCH CONTACT	1	PH/BR	50-100μ" Ni UNDERPLATING OVER ALL 50-100μ Au PLATING AT SOLDERING AREA 10μ Au PLATING AT CONTACT AREA	
4	COMMON SWITCH CONTACT	1	PH/BR	50-100μ" Ni UNDERPLATING OVER ALL 50-100μ Au PLATING AT SOLDERING AREA 10μ Au PLATING AT CONTACT AREA	
3	BOTTOM SHELL	1	SUS304	30-100μ" Ni UNDERPLATING OVER ALL 50-100μ Au PLATING AT SOLDERING AREA	
2	TOP SHELL	1	SUS301	CLEAN	
1	HOUSING	1	LCP	COLOR: BLACK	
ITEM	DESCRIPTION	Q'TY	MATERIAL	FINISH	REMARK

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 稱(TITLE) SD PUSH H:2.7	
X± 0.30	X*± 2 °		
XX± 0.20	XX*± 1 °		
單位(UNIT) mm	料 號(PART NO.) 7SDCN-F0-0037	圖 號(DWG NO.) 7SDCN-F0-0037	
審核(APPROVAL)	檢 查(CHECKED)	製 圖(DRAWN)	比 例 SCALE 1:1 圖 號 SHEET 1/1 圖 號 REV A

